



Dicer saw

ADT



Description

The ADT dicing saw is fully programmable microprocessor controlled saw intended to be used for cutting wafer thin materials into smaller component pieces.

Typically silicon wafers are diced but any thin material can be cut with the correct configuration and blade type.

The maximum thickness is only limited by the blades that are available.

Specifications / Capabilities

Substrates: silicon, quartz, sapphire, alumina ceramics, glass, metals.

Samples size: up to 8" wafers

Substrate thicknesses range: 130 μ m – 2.5 mm.

Width of the cut: about 100 μ m

Dicing precision (including the edge chipping): for silicon samples – up to 30 μ m,
for thick glasses – up to 60 μ m

Die size limitation: at wafer thicknesses over 500 μ m – 1x1mm
at wafer thicknesses less than 500 μ m – 3x3mm

Materials

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Link

<http://www.adt-co.com/>